

REMARKS

This Amendment is being filed in response to the Final Office Action mailed May 21, 2007, which has been reviewed and carefully considered. Reconsideration and allowance of the present application in view of the following remarks and arguments are respectfully requested.

In the Final Office Action, the Examiner suggested adding headings to the specification. Applicants gratefully acknowledge the Examiner's suggestion, however respectfully decline to add the headings as they are not required in accordance with MPEP §608.01(a), and could be inappropriately used in interpreting the specification.

In the Final Office Action, claims 1-3 and 5-7 are rejected under 35 U.S.C. §103(a) as allegedly unpatentable over U.S. Patent No. 6,324,072 (Lorentz) in view of U.S. Patent Application Publication No. 2002/0117743 (Nakatani). Further, claim 4 is rejected under 35 U.S.C. §103(a) as allegedly unpatentable over Lorentz in view of Nakatani and U.S. Patent No. 4,897,327 (Dubin). Claim 8-9 are rejected under 35 U.S.C. §103(a) as allegedly

unpatentable over Lorentz in view of Nakatani. It is respectfully submitted that claims 1-10 are allowable over Lorentz, Nakatani and Dubin for at least the following reasons.

Lorentz is directed to a micro-electronic component of sandwich construction. As correctly noted on page 4 of the Final Office Action, Lorentz does not teach or suggest encapsulating and separating the assembly of the substrate. Nakatani is cited in an attempt to remedy the deficiencies in Lorentz.

Nakatani is directed to a component built-in module. It is alleged, at the bottom of page 4 of the Final Office Action, that FIG 7H of Nakatani shows providing a passivating material (from the second side of the semiconductor element) through the foil, which passivating material forms an encapsulation of the elements, as recited in independent claims 1 and 8. Applicants strongly disagree.

Nakatani discloses forming various layers over each other. In particular, holes are formed in an uncured sheet of thermosetting resin 704 to form vias 705 which are filled with conductive paste and sandwiched between release carriers 700 including wiring pattern 701, a semiconductor 702 and chip component 702. The resin

sheet 704 is cured to form a component built-in core layer 706.

Other resin sheets 707, including vias 708 filled with conductive paste and release carriers 710 with components 709, are provided on both sides of the component built-in core layer 706 as shown in FIG 7H where, after heating and pressing, the release carriers 710 are peeled off. (See paragraphs [0067-0073])

There is simply no teaching or suggestion in Lorentz, Nakatani, and combination thereof, of the present invention as recited in independent claim 1, and similarly recited in independent claim 8 (illustrative emphasis provided):

providing a passivating material from the second side of the semiconductor element through the foil, which passivating material forms an encapsulation of the elements.

In Nakatani, at best, the only thing that is provided through something is the conductive paste provided in, or arguendo through, the vias 705, 708 of the resin sheets 704, 707. The Nakatani conductive paste in the vias 705, 708 does not form any encapsulation of the elements. Dubin is cited in rejecting dependent claims to allegedly show other features and does not remedy the deficiencies in Lorentz and Nakatani.

Accordingly, it is respectfully submitted that independent claims 1 and 8 are allowable, and allowance thereof is respectfully requested. In addition, it is respectfully submitted that claims 2-7 and 9-10 should also be allowed at least based on their dependence from independent claims 1 and 8 as well as for the separately patentable elements contained in each of said claims.

In addition, Applicants deny any statement, position or averment of the Examiner that is not specifically addressed by the foregoing argument and response. Any rejections and/or points of argument not addressed would appear to be moot in view of the presented remarks. However, the Applicants reserve the right to submit further arguments in support of the above stated position, should that become necessary. No arguments are waived and none of the Examiner's statements are conceded.

In view of the above, it is respectfully submitted that the present application is in condition for allowance, and a Notice of Allowance is earnestly solicited.

Respectfully submitted,

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